

# ABSTRACT

A wiring board obtained by filling a copper paste in a via hole formed on a ceramic green sheet and firing it to form an insulating layer and a via conductor, the copper paste comprising a copper powder, an organic vehicle and at least one selected from the group consisting of: a ceramic particle having an average particle size of 100 nm or less; and an  $\text{Fe}_2\text{O}_3$  particle, wherein the copper paste comprises from 6 to 20 parts by mass of the organic vehicle per 100 parts by mass of the copper powder.